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(12) **United States Design Patent**
Higashibata

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(54) **SEMICONDUCTOR MODULE**

(75) Inventor: **Kazuaki Higashibata**, Yasu (JP)

(73) Assignee: **Murata Manufacturing Co., Ltd.** (JP)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/182; 257/177, 197, 666, 684, 686, 689, 775; 361/820
See application file for complete search history.

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Primary Examiner—Selina Sikder
(74) *Attorney, Agent, or Firm*—Dickstein, Shapiro, LLP.

(57) **CLAIM**

The ornamental design for a semiconductor module, as shown.

DESCRIPTION

FIG. **1** is a front view of a semiconductor module showing our new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a left side view thereof; and,
FIG. **6** is a right side view thereof.
The broken lines shown in the drawings are for illustrative purposes only and form no part of the claimed design.

1 Claim, 2 Drawing Sheets

FIG.1

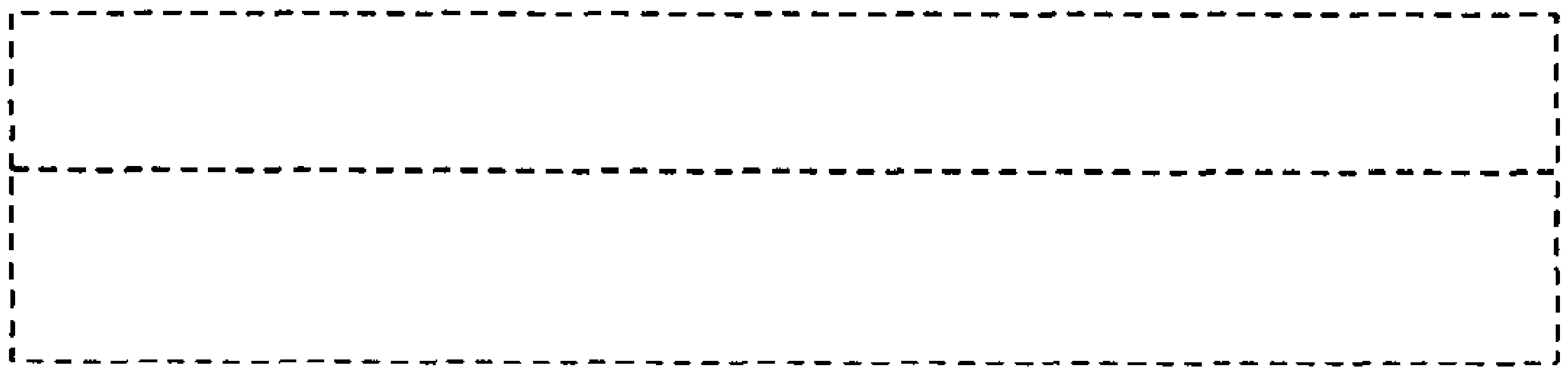

FIG.2

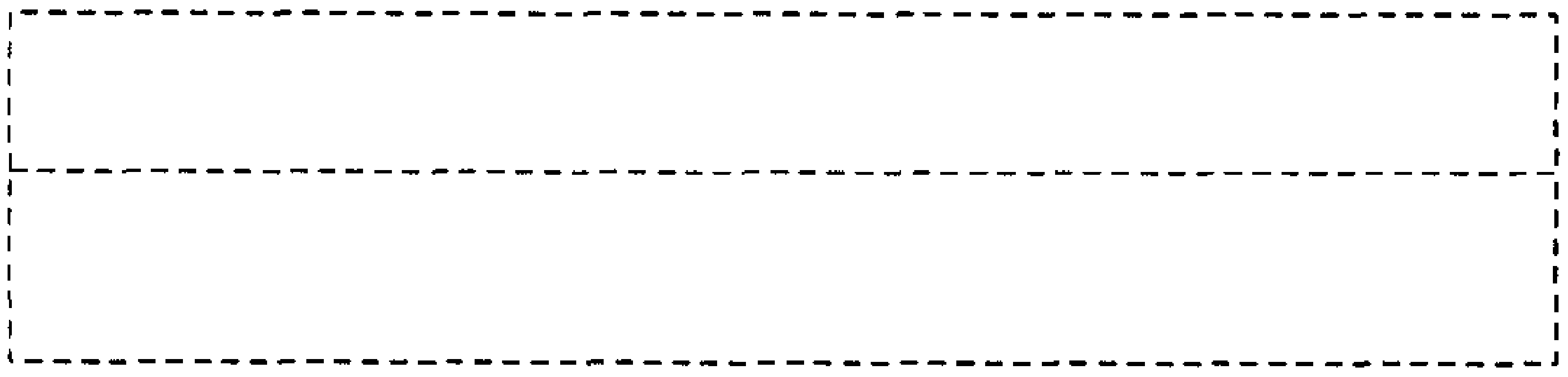

FIG.3

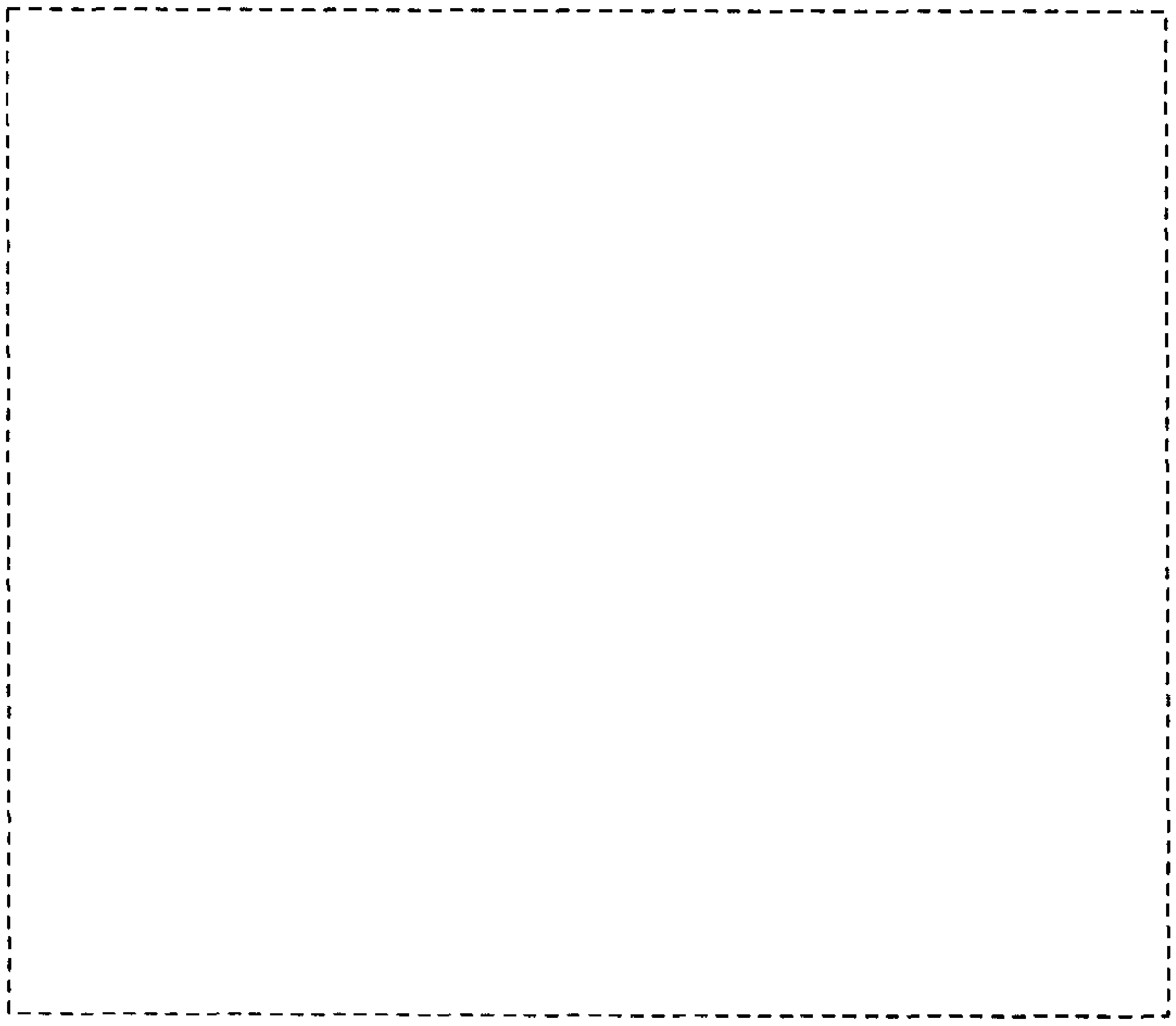

FIG.4

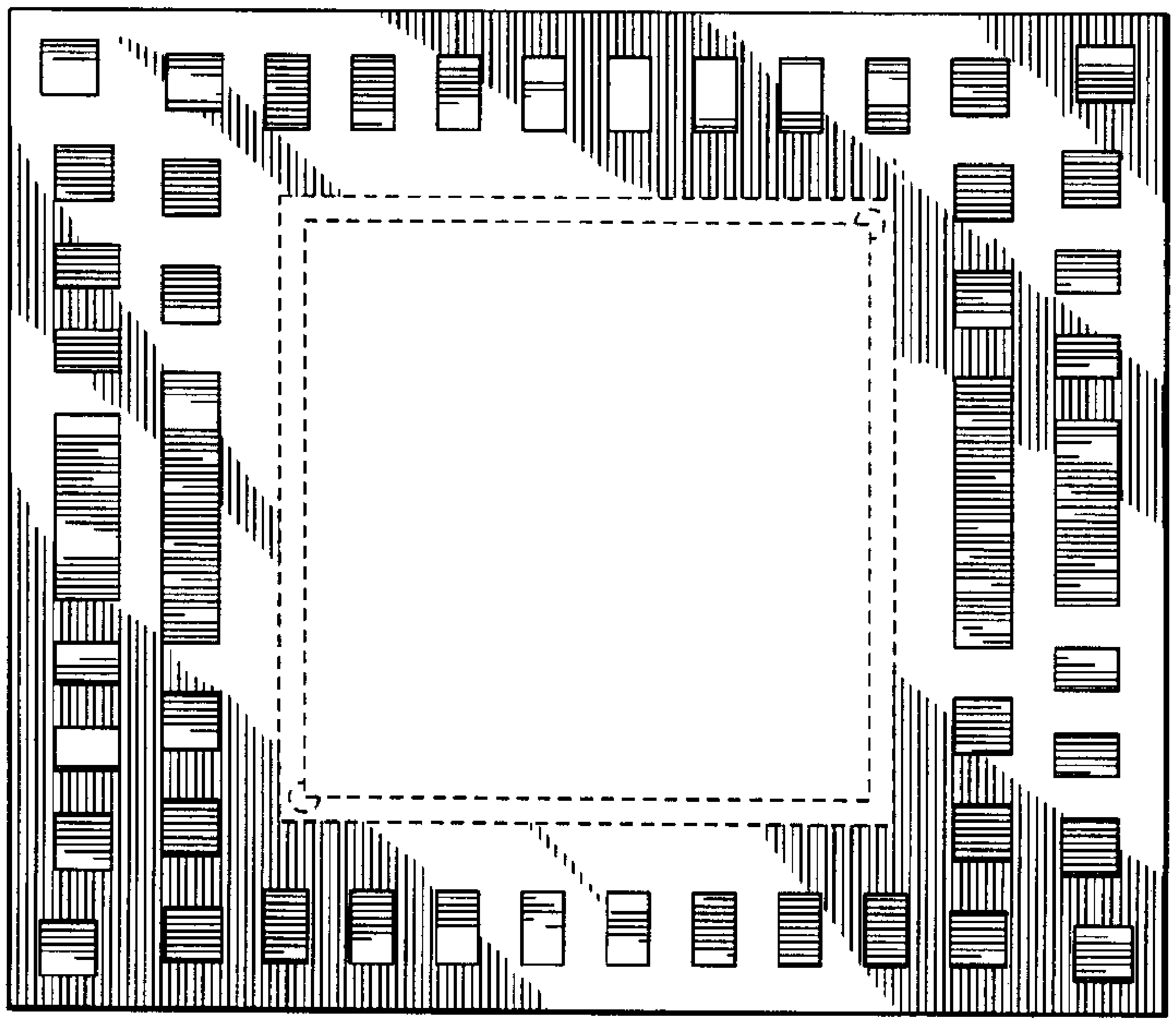

FIG.5

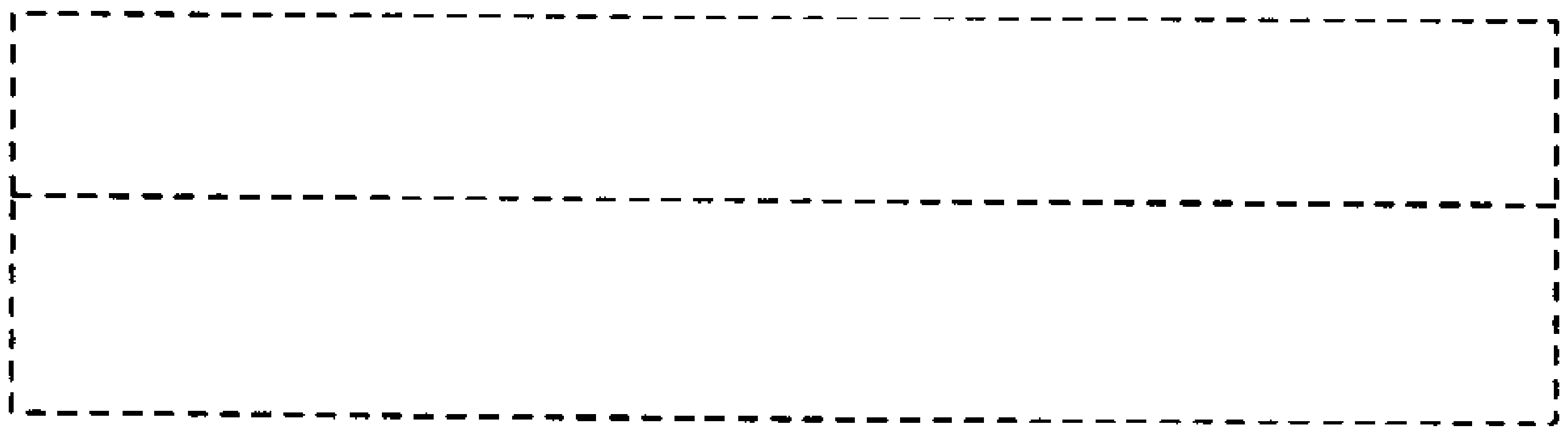

FIG.6